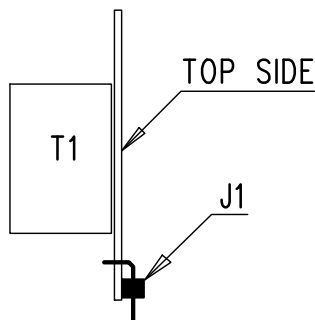
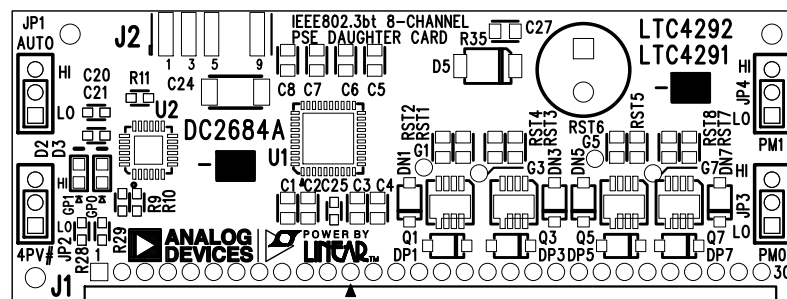
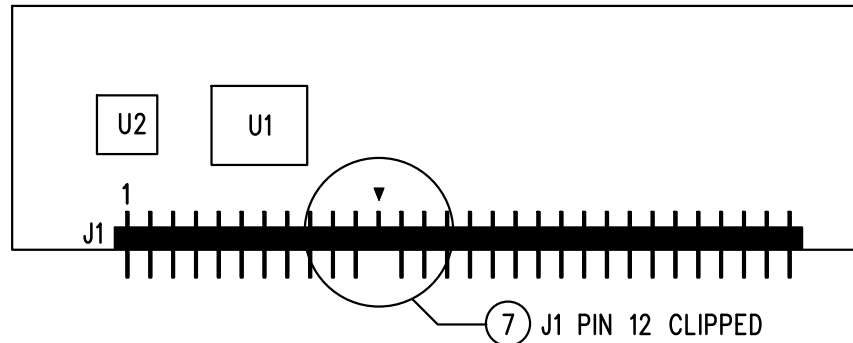


| REVISION HISTORY | | | | |
|------------------|-----|-------------|-----------|----------|
| ECO | REV | DESCRIPTION | APP. ENG. | DATE |
| - | 2 | PRODUCTION | DILIAN R. | 02-27-18 |



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. J1 PIN 12 NEED TO BE CLIPPED AS SHOWN.
8. WHITE BLOCKS ON SILKSCREEN ARE RESERVED FOR FUTURE REFERENCES

APPROVALS

PCB DES. KIM T.

APP ENG. DILIAN R.

SCALE = NONE



www.analog.com



www.linear.com

1630 McCARTHY BLVD.
MILPITAS, CA 95035
TEL: (408)432-1900

TITLE: TOP ASSEMBLY DRAWING
IEEE 802.3bt 8-CHANNEL
PSE DAUGHTER CARD

SIZE N/A IC NO. LTC4291IUF-LTC4292IUJ
DEMO CIRCUIT 2684A REV. 2

FILENAME: DC2684A-2.PCB SHT 1 OF 2